

# MATERIAL DECLARATION SHEET



Material	MF-SMDF
Product Line	Multifuse
Revision Date	7-Jul-16
Revision	B
RoHS Compliant	Yes



No.	Breakdown of part (eg Lead, Ceramic body, coating, plating, additive)	Material/substance name (eg.Sn alloy, Cu Copper)	Material/ substance weight in grams (±0.1%)	CAS No. / Int. Identifier	Material /substance weight %	Sum(%)
1	Carbon Black	Carbon	0.0014939	1333-86-4	3.84%	3.84%
2	Copper plating	Copper	0.0028159	7440-50-8	7.23%	7.23%
3	Foil	Copper	0.0186284	7440-50-8	47.84%	50.36%
		Nickel	0.0009805	7440-02-0	2.52%	
4	PCB Foil	Copper	0.0023674	7440-50-8	6.08%	6.08%
5	Polymer	Polyethylene Homopolymer	0.0012975	9002-88-4	3.33%	3.38%
		Proprietary Additives	0.0000175		0.04%	
6	Prepreg	Epoxy	0.0066892	35948-25-5	17.18%	28.63%
		Glass fiber	0.0044589	65997-17-3	11.45%	
7	Packing-Carrier Tape	Polystyrene	N/A	9003-53-6		
		Polyethylene Homopolymer	N/A	9002-88-4		
8	Packing-Cover Tape	Polyethylene terephthalate	N/A	25038-59-9		
		Polyethylene Homopolymer	N/A	9002-88-4		
9	Soldering plating	Nickel	0.0001851	7440-02-0	0.48%	0.48%
		Gold	0.0000022	7440-57-5	0.01%	
		Total Weight (%)				

Total weight (grams)	0.0389365	Total	100%	100%
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